

Amendments to the Specification

Please replace the paragraph beginning on page 8, line 15 with the following amended paragraph:

Referring to FIGURE 4, there is shown a cross-sectional view of a solder joint between solder 25 and pads 16 and 29. As generally occurs in a soldering operation, intermetallic ~~regions~~ layers are formed within both solder 25 and pads 16 and 29, intermetallic boundaries 15' being formed therein. The pads 16, 29 both have substantially planar lower and upper surfaces, respectively. Upper and lower surfaces of pads 16 and 29, respectively, have the serpentine solder configuration depicted in FIGURE 3a. It will be observed that the respective micro-cracking 20 near intermetallic boundaries 15' follow a circuitous or meandering path. The lengthening of the crack pathway increases the useful life of the solder joint. Other pad configurations are shown in FIGURES 3b through 3d. As is the case with the configuration of FIGURE 3a, these other configurations result in micro-crack pathways that are interrupted, lengthened, or constrained. In a similar manner, these configurations are expected to increase fatigue life of the solder joint, as is that of the solder design shown in FIGURE 3a.